

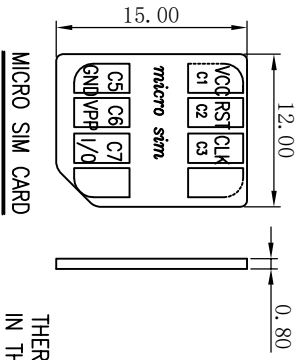
SIM pin Assignment	Pin#	Name
	C1	VCC
	C2	RST
	C3	CLK
	C5	GND
	C6	VPP
	C7	I/O

NOTES:

MATERIAL:
 Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: Stainless

PLATING:
 Contact: Plated 30u" Ni Overall ;Solder Area: Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area

Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:100MΩ min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5°



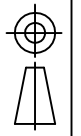
■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

UNITS:	mm
GENERAL TOLERANCE	
X° ±5°	0.X±0.25
X.L±2°	0.XL±0.2
X.X±1°	0.XX±0.1

CSCONN		CSCONN PRECISE ELECTRONICS CO.,LTD	
PART NO.(INTENDED USE)		MICRO SIM CARD 6P PUSH 1.35H 外挿式	
CS106127135005			
APPD:	SK11a	DWG NO.	SIM CARD
CHKD:	SK11a	SCALE	SHEET
DR:	Kitty	1:1	1 OF 1
			REV
			A



SCALE	SHEET	REV
1:1	1 OF 1	A